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THIS DEVICE IS **PLS** CONTACT YOUR **onsem** **DESIGN**

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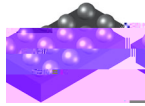


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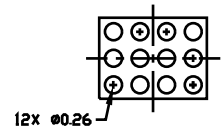
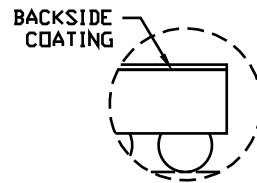
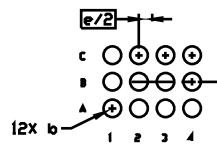
# MECHANICAL CASE OUTLINE



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. PARALLEL TO DATUM C
4. COP
5. -PLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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b-Free strategy and soldering details, please download the QN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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